2. (Amended) The process of claim 1 wherein the first polyimide film is laminated directly onto at least one etched surface of the substrate.

A1

3. (Amended) The process of claim 1 wherein the first polyimide film is laminated onto at least one etched surface of the substrate via an intermediate second polymeric film.

A2

11. (Amended) The process of claim 1 wherein the first polyimide film has a thickness of about 3 μm to about 50 μm.

A3

23. (Amended) The process of claim 22 further comprising:

i.) laminating an additional first polyimide film coated on a surface of an additional metal foil directly onto the second etched surface of the substrate, or

ii.) laminating an additional first polyimide film coated on a surface of an additional metal foil onto the second etched surface of the substrate via an intermediate second polymeric film.

24. (Amended) The process of claim 23 wherein the additional first polyimide film is laminated directly onto the second etched surface of the substrate.

25. (Amended) The process of claim 23 wherein the additional first polyimide film is laminated onto the second etched surface of the substrate via an intermediate second polymeric film.

A4

27. (Amended) A printed circuit board composite comprising a polyimide substrate having a first etched surface, a first polyamide film attached to the first etched surface of the substrate and a layer of a metal foil attached to an opposite side of the first polyimide film; and wherein the resulting printed circuit board composite has a peel strength of at least 4 lbs./inch.

28. (Amended) The printed circuit board composite of claim 27 wherein the substrate further comprises a second etched surface opposite the first etched surface, an additional first polyimide film attached to the second etched surface and an additional layer of a metal foil attached to an opposite side of the additional first polyimide film.

35. (Amended) A process for forming a printed circuit board comprising:

a) etching at least one surface of a polyimide substrate;

b) coating a first polyimide film onto a surface of a metal foil;

c) laminating the first polyimide film onto the substrate by:

i.) laminating the first polyimide film directly onto at least one etched surface of the substrate, or

ii.) laminating the first polyimide film onto at least one etched surface of the substrate via an intermediate second polymeric film;

d) depositing a photoresist onto the metal foil;

e) imagewise exposing and developing the photoresist, thereby revealing underlying portions of the metal foil; and

f) removing the revealed underlying portions of the metal foil; and

wherein the resulting printed circuit board has a peel strength of at least 4 lbs./inch.

43. (New) The process of claim 1 wherein the polyimide film is applied to the metal foil by coating a solvent solution of the polyimide onto the foil and drying wherein the solution has a viscosity ranging from about 5,000 to about 35,000 centipoise.

44. (New) The printed circuit board composite of claim 27 wherein the polyimide film has been applied to the metal foil by coating a solvent solution of the polyimide onto the foil and drying wherein the solution has a viscosity ranging from about 5,000 to about 35,000 centipoise.

45. (New) The process of claim 35 wherein the polyimide film is applied to the metal foil by coating a solvent solution of the polyimide onto the foil and drying wherein the solution has a viscosity ranging from about 5,000 to about 35,000 centipoise.